TOSHIBA Field-Effect Transistor Silicon P-Channel MOS Type (U-MOSVI)

SSM6J503NU

Power Management Switch Applications

• 1.5V drive

• Low ON-resistance: $R_{DS(ON)}$ = 89.6 m Ω (max) (@V_{GS} = -1.5 V)

 $R_{DS(ON)} = 57.9 \text{ m}\Omega \text{ (max) (@V_{GS} = -1.8 V)}$

 $R_{DS(ON)} = 41.7 \text{ m}\Omega \text{ (max) (@V_{GS} = -2.5 V)}$

 $R_{DS(ON)} = 32.4 \text{ m}\Omega \text{ (max) (@V_{GS} = -4.5 V)}$

Absolute Maximum Ratings (Ta = 25°C)

Charac	teristics	Symbol	Rating	Unit	
Drain-Source voltage		V_{DSS}	-20	V	
Gate-Source voltage		V_{GSS}	±8	V	
Drain current	DC	ID	-6.0	А	
	Pulse	I _{DP} (Note 1)	-24.0		
Power Dissipation		P _D (Note 2)	1	W	
		t ≦10s	2		
Channel temperature		T _{ch}	150	°C	
Storage temperature		T _{stg}	−55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

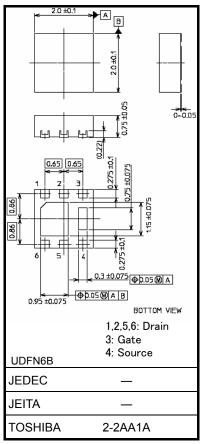
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling

Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: The pulse width limited by max channel temperature.

Note 2: Mounted on an FR4 board. $(25.4~\text{mm}\times25.4~\text{mm}\times1.6~\text{mm},~\text{Cu Pad: 645}~\text{mm}^2)$

Unit: mm

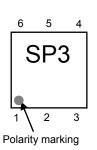


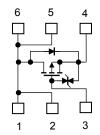
Weight: 8.5 mg (typ.)

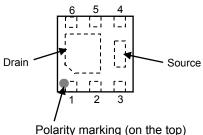
Marking(Top View)

Equivalent Circuit(Top View)

Pin Condition(Top View)







Polarity marking (on the top)
*Electrodes : on the bottom

Start of commercial production 2010-11

Electrical Characteristics (Ta = 25°C)

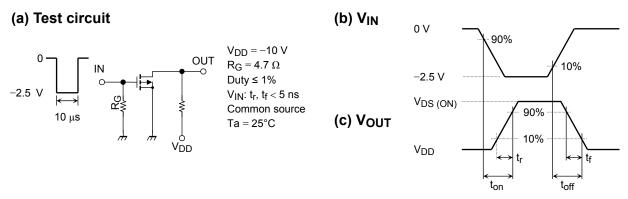
Chara	cteristic	Symbol	Test Conditions		Min	Тур.	Max	Unit
Drain-Source breakdown voltage		V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0 \text{ V}$		-20	_	_	V
		V (BR) DSX	I _D = -1 mA, V _{GS} = 5 V	(Note 4)	-15	_	_	v
Drain cut-off current		I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V		_	_	-1	μΑ
Gate leakage current		I _{GSS}	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$		_	_	±1	μΑ
Gate threshold voltage		V _{th}	$V_{DS} = -3 \text{ V}, I_{D} = -1 \text{ mA}$		-0.3	_	-1.0	V
Forward transfer admittance		Y _{fs}	$V_{DS} = -3 \text{ V}, I_{D} = -1.0 \text{ A}$	(Note 3)	4.5	9.1	_	S
Drain-source ON-resistance		RDS (ON)	I _D = -3.0 A, V _{GS} = -4.5 V	(Note 3)	_	27.7	32.4	· mΩ
			I _D = -2.5 A, V _{GS} = -2.5 V	(Note 3)	_	33.1	41.7	
			I _D = -1.5 A, V _{GS} = -1.8 V	(Note 3)	_	40.6	57.9	
			I _D = -0.5 A, V _{GS} = -1.5 V	(Note 3)	_	48.6	89.6	
Input capacitance		C _{iss}			_	840	_	
Output capacitance		Coss	V _{DS} = -10 V, V _{GS} = 0 V, f = 1	_	118	_	pF	
Reverse transfer capacitance		C _{rss}		_	99	_		
Total Gate Charge		Qg	V _{DD} = -10 V, I _D = -4.0 A V _{GS} = -4.5 V		_	12.8	_	nC
Gate-Source Charge		Q _{gs1}			_	1.4	_	
Gate-Drain Charge		Q _{gd}			_	3.0	_	
Switching time	Turn-on time	t _{on}	$V_{DD} = -10 \text{ V}, I_D = -2.0 \text{ A},$		_	32	_	20
	Turn-off time	t _{off}	$V_{GS} = 0$ to -2.5 V, $R_{G} = 4.7 \Omega$		_	107	_	ns
Drain-Source forward voltage		V _{DSF}	I _D = 4.0 A, V _{GS} = 0 V	(Note 3)	_	0.78	1.2	٧

Note 3: Pulse test

Note 4: If a forward bias is applied between gate and source, this device enters V(BR)DSX mode.

Note that the drain-source breakdown voltage is lowered in this mode

Switching Time Test Circuit



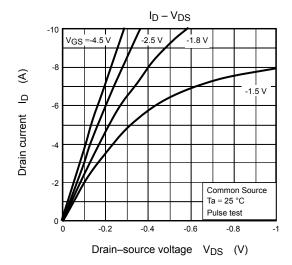
Precaution

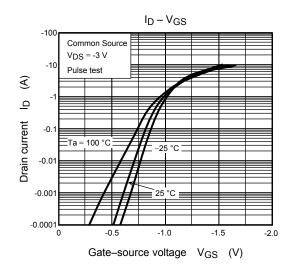
 V_{th} can be expressed as voltage between gate and source when low operating current value is I_D = -1mA for this product. For normal switching operation, V_{GS} (on) requires higher voltage than V_{th} and V_{GS} (off) requires lower voltage than V_{th} .(Relationship can be established as follows: V_{GS} (off) $< V_{th} < V_{GS}$ (on)) Please take this into consideration for using the device.

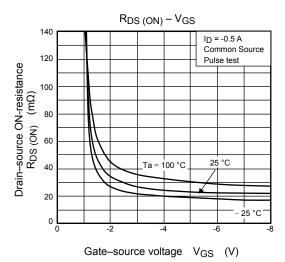
Handling Precaution

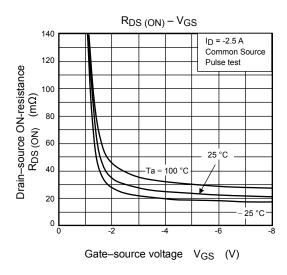
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

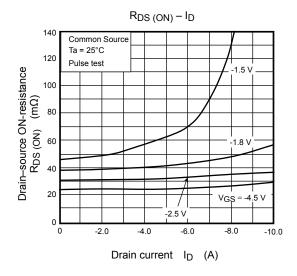
Thermal resistance $R_{th\ (ch-a)}$ and power dissipation P_D vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration

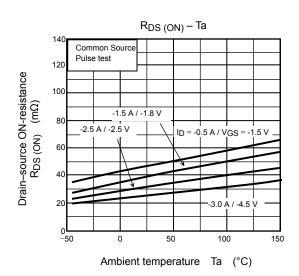


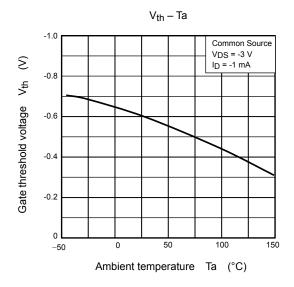


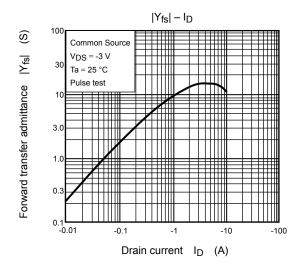


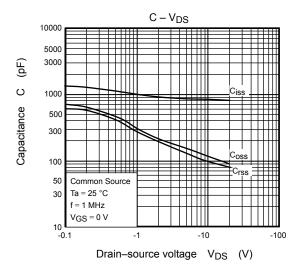


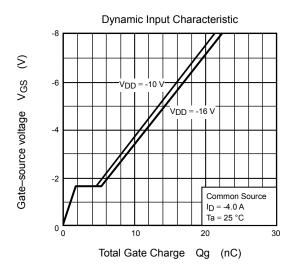


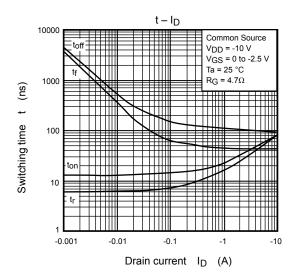


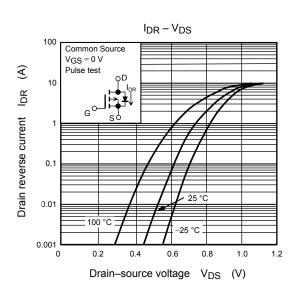


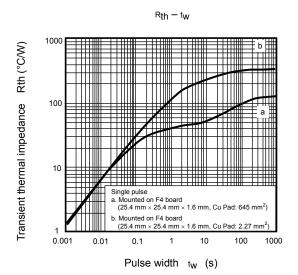


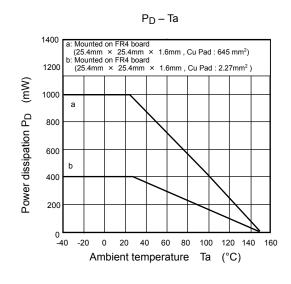












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